FLAGLESS SEMICONDUCTOR PACKAGE

Abstract of the Disclosure

A molded semiconductor package having a flagless leadframe (22) wherein a semiconductor die (10) is disposed in or above a die opening (20) of a leadframe (22). This allows for thin, symmetrical packages and packages having a minimum number of material interfaces to be manufactured because no leadframe flags and minimal die bond material are employed. The present invention further includes guard rings (34) to protect high stress areas of the semiconductor die (10) from damage and heat spreaders (46) to more effectively spread heat dissipated by the semiconductor die (10).

FIG. 1 accompanies this abstract.